# <별지서식 11: 규격서>

# (연구장비)규격서

품 명	영 문	W-Cs TEM for Low kV analysis	수 량	1	구분	국내물품( )	
	국 문	저가속전압 분석용 수차보정 투과전자현미경	T 0	J	十正	국외물품(○)	
모델명							
원산지							
제조 회사							
		주요구성 부분 및 SPECIFICATION					

# 1. 용 도

- 1. The Atomic Resolution Analytical Microscope for the multi-purpose analytical works should be transmission electron microscope (TEM) for scanning electron probe in scanning transmission electron microscope (STEM), to reveal sub-angstrom atomic structure and chemical information.
- 2. The diameter of the electron column should be large enough to deliver its mechanical and thermal stability, while the base frame should be designed to isolate the whole system from external mechanical noise. Furthermore, magnetic and heat-insulation shields are optimally placed on the column, to obtain the best performance by blocking the external disturbance.
- 3. This system should be equipped with TEM&STEM Cs corrector which provides extremely small probe size, enabling TEM&STEM imaging, EDS analysis and EELS analysis. In addition, this Cs corrected TEM should be able to equipped Cold type field emission gun to increase the probe current density, allowing for enhanced analysis with a higher signal-to-noise ratio.
- 4. The W-Cs TEM should be able to provide bright-field(BF) and dark-field(DF) TEM images and High angle, medium angle, and low angle annular dark field scanning transmission (STEM) image, simultaneously linked with the chemical information mapping from the same region of the specimen.
- 5. A imaging-detection chamber enables at least 3 different STEM image detectors in the electron beam path. Thus both the BF and DF image should be obtained at that time under the optimum optical condition.
- 6. To analyze samples that are sensitive to beam damage, this STEM system should be able to acquire aberration-corrected TEM and STEM images at an accelerating voltage of 30 kV.

#### 2. 세부규격(성능 및 사양)

1. Performance

1) Resolution TEM Point image:

TEM Lattice image:

0.10nm or better

0.07nm or better

STEM BF image:

0.078nm or better

STEM DF image:

0.78nm or better (@200kV)

2) Size for Ronchigram

More than 50mrad at all Acc. Volt.

3) Accelerating Voltage:

30 ~ 200kV or wider

4) Cs corrector tuning:

200kV, 80kV, 60kV, 30kV or wider 1.0nA for 0.136nm probe dia.

5) Probe current :6) Power Stability

Acc. Voltage: 5 x 10<sup>-7</sup>/minorbetter

OL current : 5 x 10<sup>-7</sup>/minorbetter

7) Spot size :

Min. 0.1nm dia. or smaller

8) Magnification

TEM mode :  $x50 \sim x2,000,000$  or wider

TEM SA MAG mode : x8,000 ~ x800,000 or wider

STEM mode :  $x200 \sim x15,000,000$  or wider

STEM MAG mode :  $x20,000 \sim x150,000,000$  or wider

9) Specimen movement

 $X, Y : \pm 1mm$  $Z : \pm 0.1mm$ 

Tilt angle: ± 25°

2. Electron Gun

1) Emitter:

Cold field emission type

2) Brightness:

8 x 10<sup>8</sup>A/cm<sup>2</sup> · sr or higher

3) Energy resolution:

0.3 eV or less at analytical condition.

4) Acc. tube & stage :

7 stages Accelerating tube or better

3. Condenser Lens

1) Lens system:

3 stage (1st CL, 2nd CL, Condenser mini lens)

2) Variable apertures:

Motor drive, metal bellow

10, 20, 30, 40, 50, 70, 100, 150 um in dia. or better.

Emission noise canceller function

3) Stigmator :

Two-fold astigmatism correction circuit

4) Beam tilting:

±5°

5) Alpha Selector:

TEM mode : 2 steps or better

Probe mode: 4 steps or better

Trobe illoue : 4

6) Hard X-ray aperture:

Motor drive, Mo aperture 200um in diameter

4. Specimen Chamber

1) Specimen stage :

Full 6-axis control side-entry eucentric

with Z-axis and bake-out heater

2) Specimen exchange:

Airlock and , automatic double-stage pre-evacuation system.

3) Anti-contamination device (ACD) system :

LN2 cooled fin and large LN2 tank

LN2 Holding Time: 14h or more

4) Specimen Holder:

Specimen size: 3mm dia. Grid

No. of Specimen Loadable: one (1)

5) Goniometer:

Intelligent type

Piezoelectric element

6) Specimen Movements

-. For X/Y direction : -. For Z direction:

Motor drive and piezo drive  $\pm 1$  mm Motor drive and piezo drive  $\pm 0.1$  mm

-. Tilt-X/Y:

Motor drive

5. Objective Lens

1) Lens system:

Two- stage lens system (OL lens and OL mini-lens)

2) Pole pieces:

Ultra High resolution Pole piece

3) OL High contrast aperture: Motor drive, 5, 20, 60, 120 um in diameter

4) Electromagnetic field shift :  $\pm 2um(X/Y)$ 

6. Image-Forming lens:

Intermediate Lens (IL) and Projector Lens (PL)

1) Lens system:

4-stage (1st, 2nd, 3rd IL and PL)

2) Imaging:

Rotation-free, distortion-free Motor drive, Mo disc aperture

3) Selected-area aperture:

10. 20. 50. 100 um in diameter

4) Axis alignment:

Mechanical and electromagnetic

5) Shutter:

Built into Projector Lens

6) Airlock valve:

Built-in

7. Viewing Chamber

1) Viewing window:

Front, 178 mm in diameter

2) Fluorescent screen:

Large screen: 160 mm diameter Small screen: 25 mm diameter

Binoculars: 10x

8. Image Detection chamber

Port for BF STEM detector & STEM image aperture

Port for Beam stopper

9. STEM Image Acquisition Unit

1) Image acquisition detector: BF TEM detector & DF TEM detector

2) Beam Scanning:

Digital scan

Scan-signal external input possible

3) Scanning modes:

Surface scan , Line scan , Spot , Externally controlled scan

10. Vacuum System

1) Evacuation:

Differential pumping

2) Control:

Fully automatic sequential control

3) Bake-out system:

Automatic control

4) Vacuum pumps Electron gun chamber : 300L/s NEG pump

Electron gun acceleration tube : 200L/s SIP

Intermediate chamber : 20L/s SIP
2nd intermediate chamber : 30L/s SIP

Column: 150 L/s SIP

Viewing chamber/Image detection chamber: 420 L/s DP

5) Vacuum gauges : Pirani gauges and Penning gauges

6) Electron gun chamber : 1x10<sup>-8</sup>Pa orless 7) Specimen chamber : 2x10<sup>-5</sup>Pa orless

8) Venting by gas: Dry nitrogen gas automatic termination mechanism

11. Operation Control System

1) Operation computer: PC , Windows® 64 bit or later

2) Operation: Operation panel and graphical user interface (TEM Center)

12. Safety Device

1) Protective devices: Against power and water failures

2) Self-diagnosis function: Pneumatic failure

Cooling water failure

Rotary pump rotation failure

Temperature rise of oil-diffusion pump

Pirani gauge failure

Increased pressure of reservoir tank

13. EDS for TEM

1) SDD Detector: 100mm<sup>2</sup>ActiveareaX2(Dualdetectorsystem)

Windowless, peltier cooling type (No LN2)

2) Solid angle: 1.24sr or better3) Energy resolution: 133eV or better

4) Detectable elements : 5B to 92U or wider

5) Application software : EDS spectral analysis

Line analysis

Elemental Mapping with Probe tracking

Quantitative mapping

14. TEM Camera

1) Type: 16M pixels One view Camera

2) Sensor active area: 61.4 X 61.4 mm
3) Sensor size: 4096 X 4096 pixels

4) Pixel size : 15um

5) Full sensor read-out speed: 25fps

6) Image display : 25fps

7) Image Capture modes : Exposure time

Signal-to-noise Specimen dose 8) GIF compatible :

possible

9) System Configuration

16M pixel TEM CCD camera

In-situ up-grade DIFPack software PC for TEM Camera

Installation & Training

#### 15. Electron energy loss spectroscopy for Cs-FE TEM

1) GIF Quantum ER System

2) Entrance aperture size :

9.0/ 5.0/ 2.5mm

3) Min. slit width:

2.0 eV (200kV)

4) Max. Slit width:

100eV (200kV)

5) Mask image distortion RMS (%):

0.50%

6) Mask image distortion max. (%):7) System Configuration

0.75%

STEM Pack Up grade

Dual-EELS Up grade

Software Suite for DualEELS

High Speed Up grade

Charge for each additional voltage (60kV, 30kV)

Advanced AutoFilter Suite

EELS Advisor Suite

EDS Acquisition Online Suite

Test Specimen (NIO&BN)

#### 3. 표준 및 부속품(주요 자재 및 설비)

#### 1. 주장비

1) Electron Microscope Basic Unit	1 set			
2) Cold Field Emission Gun with HT tank	1 set			
3) Noise Canceller system	1 set			
4) Double corrector HT Cable	1 set			
5) Ultra High Resolution Pole-piece	1 set			
6) Beam Stopper	1 set			
7) ASCOR UHR STEM Cs Corrector	1 set			
8) UHR TEM Cs Corrector	1 set			
9) STEM & TEM Cs Corrector assembly parts	1 set			
10) Objective lens	1 set			
11) Double Cs corrector column cover	1 set			
12) Computer Unit with main monitor				
13) Electrode Short Switch				
14) Foot Switch Pedal				
15) Power Supporter	1 set			

	16) Dry pumping station		1 set	
	17) Ion cleaner		1 set	
	18) BF STEM detector system		1 set	
	19) Dark Field Image Observation Device		1 set	
l	20) Reinforced Specimen Tilting Holder		1 set	
	21) Reinforced Specimen Tilting Beryllium Hole	der	1 set	
	22)60 kV STEM & TEM Cs Corrector Data		1 set	
	23) 30kV Electron source data		1 set	
	24)30kV STEM & TEM Cs corrector Data		1 set	
	25) Energy dispersive Spectrometer system		1 set	
l	100mm <sup>2</sup> windowlessDrySDDetector	2 set		
	SD100 UHR Accessory	2 set		
	Digital Pulse Processor 5	2 set		
	Standard Software with Mapping	1 set		
	Personal Computer for EDS system	1 set		
	Dual Detector Mixer with adapter	1 set		
	26) TEM Camera system		1 set	
	16megapixel TEM camera system	1 set		
	In-situ up-grade	1 set		
	True-Align software	1 set		
	DIFPack Software	1 set		
	27) Electron energy loss spectrometer system	4	1 set	
	GIF Quantum ER system	1 set		
	<ul><li> Data for low kV analysis (30kV, 60kV)</li><li> High speed STEM pack upgrade</li></ul>	1 set 1 set		
	GIF Quantum upgrade for Dual EELS	1 set		
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2	. 부속장비			
	1) UPS for W-Cs STEM		1 set	
	2) Cooling Water circulator		1 set	
	3) UPS for cooling Water circulator		1 set	
	4) Air compressor		1 set	
1				

## 4. 선택부속 또는 추천부속품(주요 공사)

## 5. A/S기간 등 기타사항

Installation and Supervision
 Installation, Supervision and test-run will be carried out by a qualified engineer.

 At that time of installation the engineers shall provide such service as installation, adjustment and adequate tuition for the operator.

2. Warranty of Equipment.

Warranty service for the goods manufactured by maker will be provided within twelve(12) calendar months from the date of installation or fifteen(15) calendar months from the date of dispatch, whichever comes first.

3. Operation Training

Operation training of equipment will be carried out by a qualified engineer at that time of installation free of charge.

## ※ 작성 요령

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